

ABSTRACT OF THE DISCLOSURE

A method for removing an image sensor from a printed circuit board. The printed circuit board has a first surface and a second surface. The image sensor is welded to the first surface, and the method includes the steps of: supplying a hot
5 air stream to the first surface of the printed circuit board so as to distribute the hot air stream over a periphery of the image sensor and to melt solder; and providing a heater to heat the second surface of the printed circuit board and to raise a temperature of the second surface of the printed circuit board.